

SPECIFICATION FOR COLOR LCD MODULE

MODEL NO: TM240320BNFWG

CUSTOMER: _____

TIANMA MICROELETRONIC CO., LTD
22/F HANGDU BUILDING, CATIC ZONE,
SHEN NAN ROAD CENTRAL
SHENZHEN, CHINA
TEL: (86-755) 83790774
FAX: (86-755) 83790431
WEB: WWW.TIANMA.COM



PREPARED	CHECKED	VERIFIED BY R&D DEPT	VERIFIED BY QC DEPT	APPROVED

REVISION RECORD

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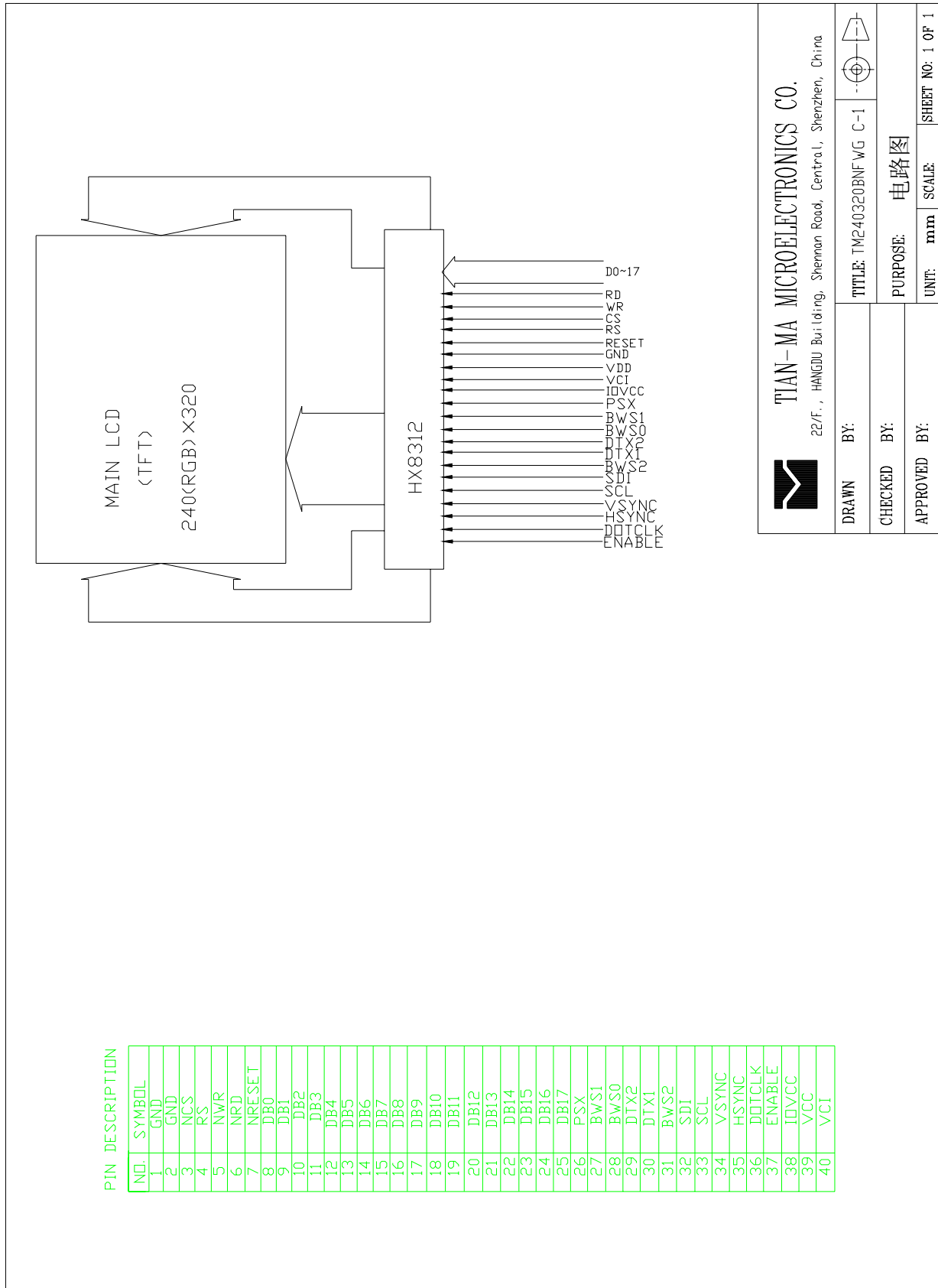
1.General Specifications

Item	Main LCD	Unit	Note
LCD Type	TFT(LTPS)	-	
Display color	262K		1
LCD Duty	1/320	-	
LCD Bias	-	-	
Viewing Direction	6:00	O'Clock	
Viewing Area(W×H)	-	mm	
Active Area(W×H)	33.48X44.64	mm	
Number of Dots	240(RGB)×320	mm	
Dot Size(W×H)	-	mm	
Dot Pitch(W×H)	0.0465X0.1395	mm	
Controller	HX8312-A	-	
V _{DD}	2.7~3.3V	V	
Outline Dimensions	Refer to outline drawing on next page		
Backlight	LED(white)	-	
Operating Temperature	-20~+70℃	-	
Storage Temperature	-30~+80℃	-	
Weight	TBD	g	2
Data Transfer	18 bits parallel	-	
Polarizer Mode	Transmissive/Positive	-	

Note 1: Select by software, and color tune is slightly changed by temperature and driving voltage.

Note 2: TBD- To Be Determined.

3. Circuit Block Diagram



4. Absolute Maximum Ratings(Ta=25℃)

Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage(1)	V _{BAT}	-	-	V	1,2
Power Supply Voltage(2)	V _{DD}	2.4	3.3	V	
Power Supply Voltage for Mail LCD	V _{op}	-	-	V	
Logic Signal Input Voltage	V _I	-0.3	V _{DD} +0.3	V	
Operating Temperature	Top	-20	+70	℃	
Storage Temperature	Tst	-30	+80	℃	

Notes:

1. If the module is above these absolute maximum ratings. It may become permanently damaged. Using the module within the following electrical characteristic conditions are also exceeded, the module will malfunction and cause poor reliability.
2. V_{DD} > V_{SS} must be maintained.

5. Electrical Specifications and Instruction Code

5.1 Electrical characteristics (Ta=25°C)

Parameter		Symbol	Condition	Min	Typ	Max	Unit	Note
Operation voltage for Main LCM		V _{DD}	Ta=25℃	2.4	2.8	3.3	V	1
Input voltage	‘H’	V _{IH}	IOVCC=1.6~3.3V	0.8IOVCC	-	IOVCC	V	
	‘L’	V _{IL}	IOVCC=1.6~3.3V	-0.3V	-	0.2IOVCC	V	
Output Voltage	‘H’	V _{OH}	I _{OH} =-0.1mA	0.8IOVCC	-	-	V	
	‘L’	V _{OL}	I _{OL} =0.1mA	-	-	0.2IOVCC	V	
Current Consumption		I _{CC1}	Normal mode	-	70	80	mA	2
		I _{CC2}	Stand-by mode	-	2.5	4	mA	3
		I _{CC3}	Dimming mode	-	-	-	mA	4

Note:

- 1: IC default setting, Duty:1/320
- 2: Display full white. Backlight on state.
- 3: IC on standby mode, VBAT=3.8V.
- 4: Display full white. Backlight dimming state.

5.2 Interface Signal

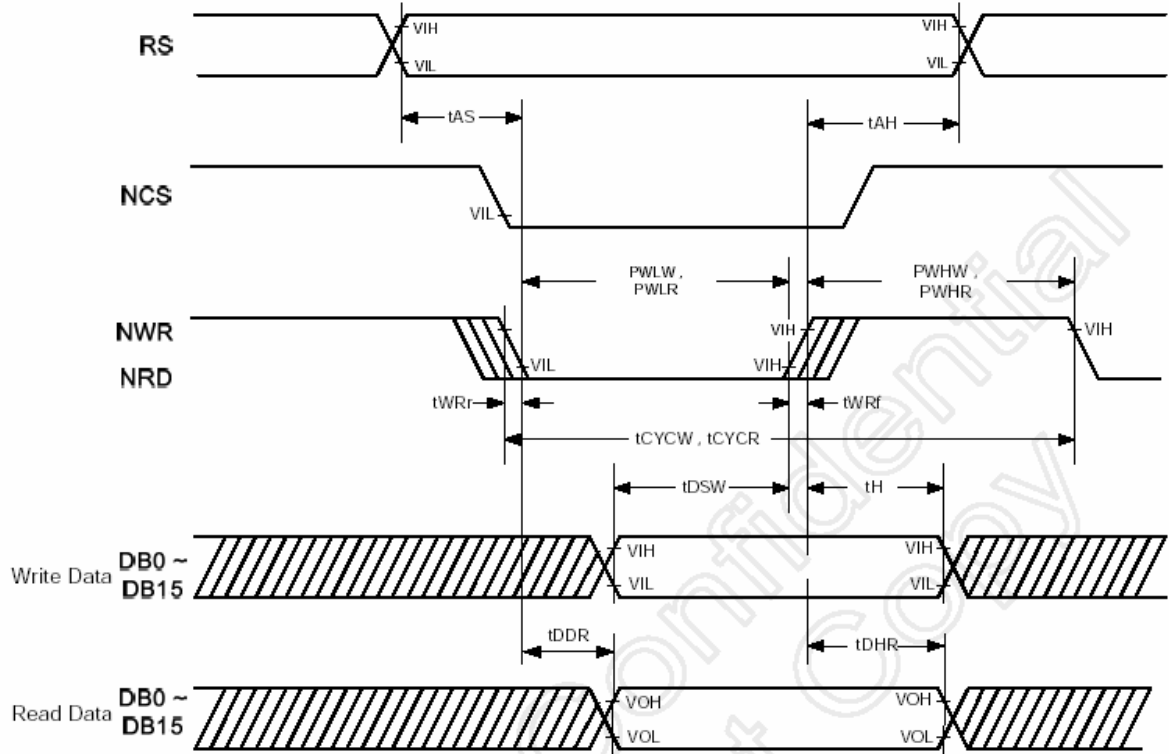
Pin No.	Symbol	I/O	Function
1	GND	I	Power Ground
2	GND	I	Power Ground
3	CS	I	Chip select input pin
4	RS	I	Instruction /data select input pin
5	WR	I	Write execution control pin
6	RD	I	Read execution control pin
7	RESET	I	System reset
8	D0	I/O	DATA BUS
9	D1	I/O	
10	D2	I/O	
11	D3	I/O	
12	D4	I/O	
13	D5	I/O	
14	D6	I/O	
15	D7	I/O	
16	D8	I/O	
17	D9	I/O	
18	D10	I/O	
19	D11	I/O	
20	D12	I/O	
21	D13	I/O	
22	D14	I/O	
23	D15	I/O	
24	D16	I/O	
25	D17	I/O	
26	PSX	I	The parallel and serial bus interface selection in system interface circuit
27	BWS1	I	The bus width selection in system interface circuit
28	BWS0	I	

29	DTX2	I	Specify the transferring method of one pixel data in system interface
30	DTX1	I	
31	BWS2		The bus width selection in RGB interface circuit
32	SDI		Serial bus interface data input pin
33	SCL		Serial bus interface clock input pin
34	VSNC		Vertical synchronization signal input pin
35	HSNC		Horizontal synchronization signal input pin
36	DOTCLK		Dot clock signal input used in the RGB interface circuit
37	ENABLE		Enable signal pin used in the RGB interface circuit
38	IOVCC		A Power supply for I/O circuit
39	VCC		A Power supply for the internal logic circuit
40	VCI		A Power supply for set-up circuit and power supply circuit

Note: Please refer to HIMAX HX8312-A data sheet for more details.

5.3 Interface Timing Chart

80-system Bus Operation

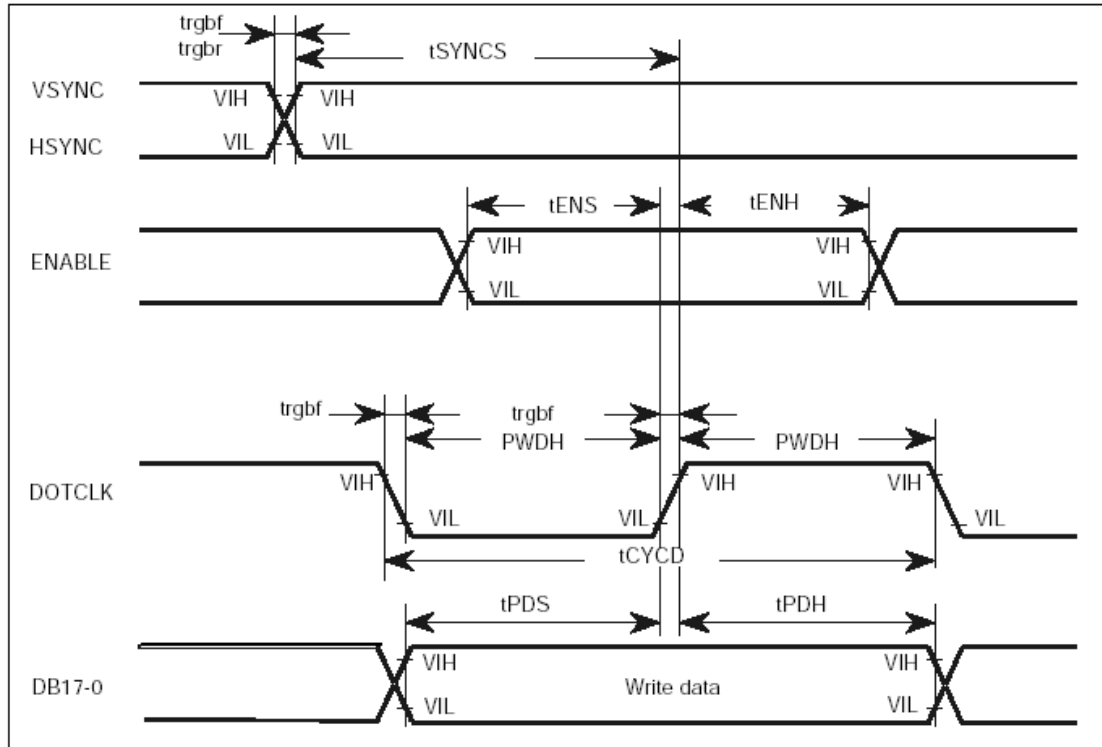


80-system Bus Interface Timing Characteristics

Item	Symbol	Unit	Min.	Typ.	Max.	Test Condition
Bus cycle time	Write	t_{CYCW}	ns	200	-	Figure 17.1
	Read	t_{CYCR}	ns	300	-	Figure 17.1
Write low-level pulse width	PW_{LW}	ns	40	-	-	Figure 17.1
Read low-level pulse width	PW_{LR}	ns	150	-	-	Figure 17.1
Write high-level pulse width	PW_{HW}	ns	70	-	-	Figure 17.1
Read high-level pulse width	PW_{HR}	ns	150	-	-	Figure 17.1
Write / Read rise / fall time	t_{WRr}, t_{WRf}	ns	-	-	25	Figure 17.1
RS Setup time (RS to NCS, NWR)	t_{AS}	ns	5	-	-	Figure 17.1
RS hold time (NCS, NWR to RS)	t_{AH}	ns	5	-	-	Figure 17.1
Write data set up time	t_{DSW}	ns	20	-	-	Figure 17.1
Write data hold time	t_H	ns	15	-	-	Figure 17.1
Read data delay time	t_{DDR}	ns	-	-	100	Figure 17.1
Read data hold time	t_{DHR}	ns	5	-	-	Figure 17.1

Table 17. 3. 1 Normal Write Mode (IOVCC = 1.65 ~ 2.4V) / (VCC = 2.4V~3.3V)

RGB Interface Operation

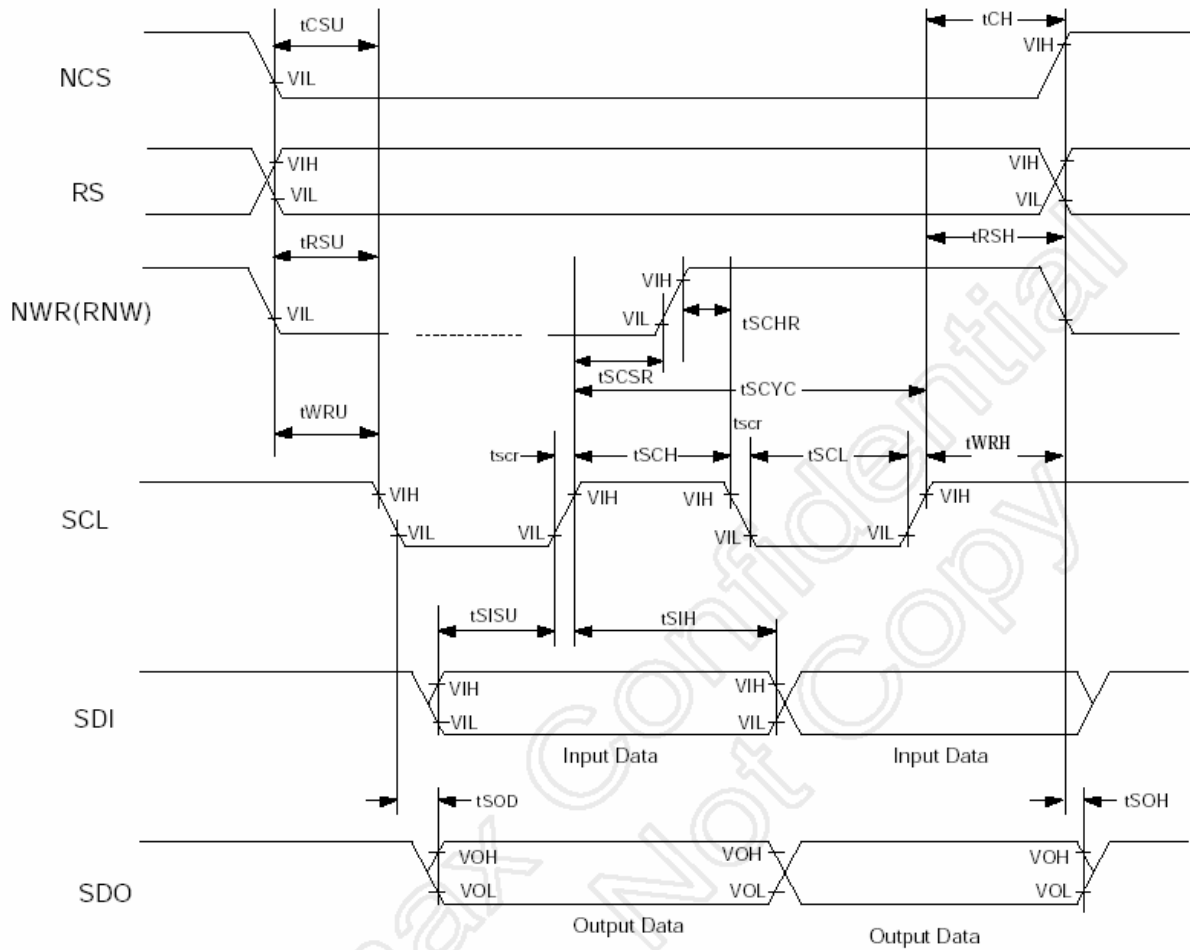


RGB Interface Timing Characteristics

Item	Symbol	Unit	Min.	Typ.	Max.	Test Condition
VSYNC / HSYNC set up time	t_{SYNCS}	ns	10	-	-	Figure 17.4
ENABLE set up time	t_{ENS}	ns	10	-	-	Figure 17.4
ENABLE hold time	t_{ENH}	ns	10	-	-	Figure 17.4
DOTCLK "low" level pulse width	PW_{DL}	ns	40	-	-	Figure17.4
DOTCLK "high" level pulse width	PW_{DH}	ns	40	-	-	Figure17.4
DOTCLK cycle time	t_{CYCD}	ns	200	-	-	Figure17.4
DATA set up time	t_{PDS}	ns	20	-	-	Figure17.4
DATA hold time	t_{PDH}	ns	20	-	-	Figure17.4
DOTCLK , VSYNC , HSYNC rising and falling time	t_{rgbr} , t_{rgbf}	ns	-	-	25	Figure17.4

Table 17. 6. 1 RGB interface mode, Normal Write Mode (IOVCC=1.65~2.4V) / (VCC = 2.4V~3.3V)

Clock Synchronized Serial Data Transfer Interface Operation



Serial Data Transfer Interface Timing Characteristics

Item	Symbol	Unit	Min.	Typ.	Max.	Test Condition
Serial clock cycle time	Write (received)	t _{SCYC}	ns	100	-	Figure 17.3
	Read (transmitted)	t _{SCYC}	ns	200	-	Figure 17.3
Serial clock high – level pulse width	Write (received)	t _{SCH}	ns	40	-	Figure 17.3
	Read (transmitted)	t _{SCH}	ns	150	-	Figure 17.3
Serial clock low – level pulse width	Write (received)	t _{SCL}	ns	40	-	Figure 17.3
	Read (transmitted)	t _{SCL}	ns	150	-	Figure 17.3
Serial clock rise / fall time	t _{scr} , t _{scf}	ns	-	-	20	Figure 17.3
Chip select (NCS) set up time	t _{CSU}	ns	20	-	-	Figure 17.3
Chip select (NCS) hold time	t _{CH}	ns	60	-	-	Figure 17.3
RS set up time	t _{RSU}	ns	10	-	-	Figure 17.3
RS hold time	t _{RSH}	ns	10	-	-	Figure 17.3
Read/write select (RNW) set up time	t _{WRU}	ns	10	-	-	Figure 17.3
Read/write select (RNW) hold time	t _{WRH}	ns	10	-	-	Figure 17.3
Read clock set up time	t _{SCSR}	ns	10	-	-	Figure 17.3
Read clock hold time	t _{SCHR}	ns	10	-	-	Figure 17.3
Serial input data set up time	t _{SISU}	ns	30	-	-	Figure 17.3
Serial input data hold time	t _{SIH}	ns	30	-	-	Figure 17.3
Serial output data delay time	t _{SOD}	ns	-	-	100	Figure 17.3
Serial output data hold time	t _{SOH}	ns	5	-	-	Figure 17.3

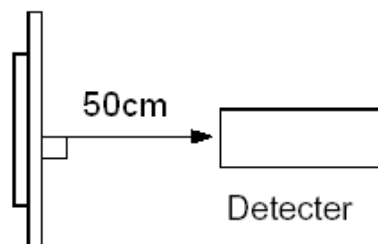
Table 17. 5. 1 (IOVCC=1.65~3.3V) / (VCC = 2.4V~3.3V)

6. Optical Characteristics

6.1 Main LCD

Item	Symbol		Condition	Min.	Typ.	Max.	Unit	Note
Brightness	Bp		$\Phi_1=0^\circ$	150			Cd/m ²	1
Uniformity	$\triangle$ Bp		$\Phi_2=0^\circ$	70%				1,2
Viewing Angle	Φ_1 (up down)		Cr $\geq$ 2	-15 $\sim$ +35			Deg	3
	Φ_2 (left right)			-45 $\sim$ +45				
Contrast Ratio	Cr		$\Phi_1=0^\circ$	40	50	70	-	4
Response Time	Tr+ T _f		$\Phi_2=0^\circ$	-	40	60	ms	5
Color of CIE Coordinate	W	x	$\Phi_1=0^\circ$ $\Phi_2=0^\circ$	0.26	0.30	0.34	-	1,6
		y		0.26	0.30	0.34	-	
	R	x		0.46	0.50	0.54	-	
		y		0.29	0.33	0.37	-	
	G	x		0.27	0.31	0.35	-	
		y		0.47	0.51	0.55	-	
	B	x		0.12	0.16	0.20	-	
		y		0.14	0.18	0.22	-	
NTSC Ratio	S				50%			

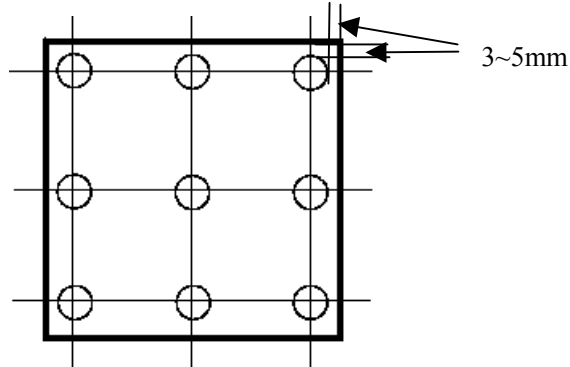
Note 1: The data are measured after LEDs are turned on for 5 minutes. LCM displays full white. The brightness is the average value of 9 measured spots. Measurement equipment PR-705 ($\Phi 10\text{mm}$)



Note 2: $\Delta Bp = Bp \text{ (Min.)} / Bp \text{ (Max.)} \times 100 \text{ (\%)}$

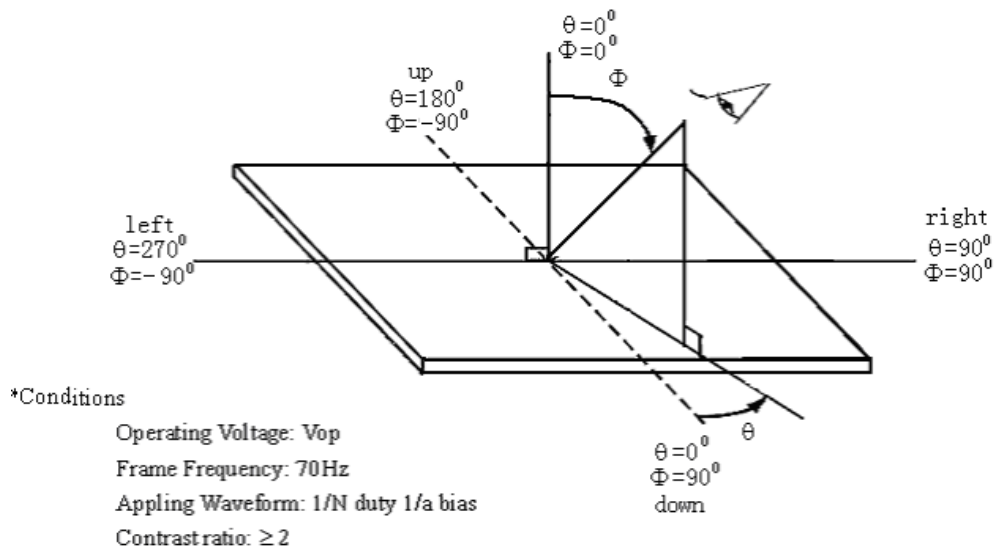
$Bp \text{ (Max.)}$ = Maximum brightness in 9 measured spots

$Bp \text{ (Min.)}$ = Minimum brightness in 9 measured spots.

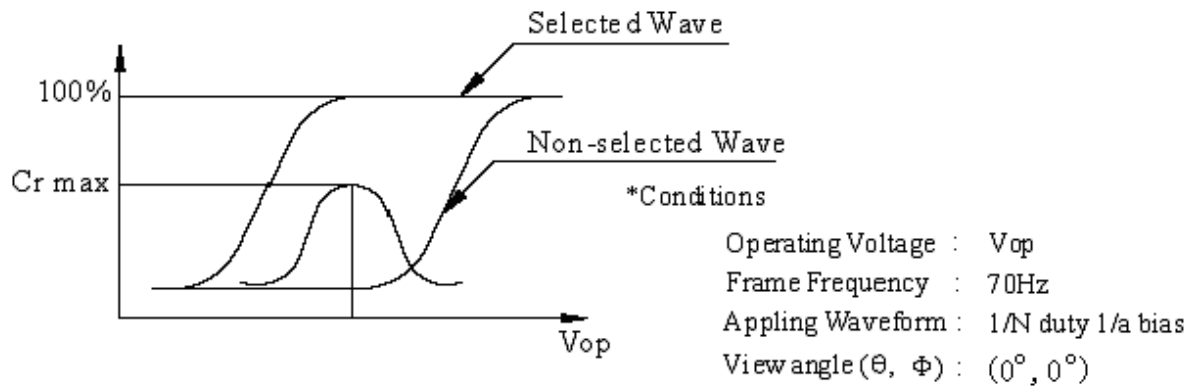


Measurement equipment PR-705 ($\Phi 10\text{mm}$)

Note 3: Definition of Viewing Angle(Test LCD using DMS501)

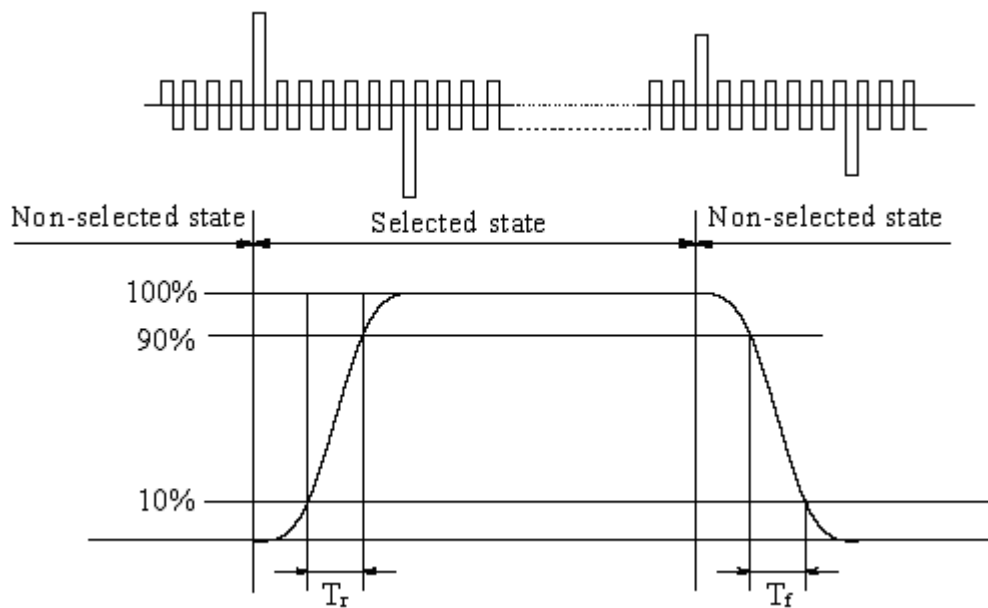


Note 4: Definition of contrast ratio.(Test LCD using DMS501)



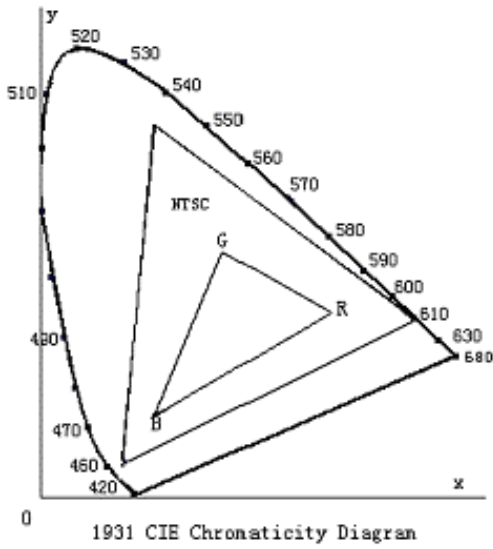
$$\text{Contrast ratio}(Cr) = \frac{\text{Brightness of selected dots}}{\text{Brightness of non-selected dots}}$$

Note 5: Definition of Response time(Test LCD using DMS501)



Operating Voltage: Vop
Frame Frequency: 70Hz
Applying Waveform: 1/N duty 1/a bias
View angle (θ, Φ): (0°, 0°)

Note 6: Definition of Color of CIE Coordinate and NTSC Ratio.



Color gamut:

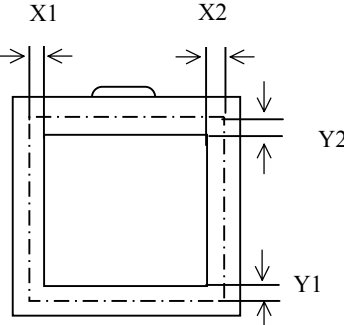
$$S = \frac{\text{area of RGB triangle}}{\text{area of NTSC triangle}} \times 100\%$$

7. Reliability

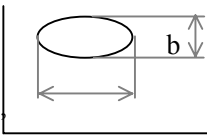
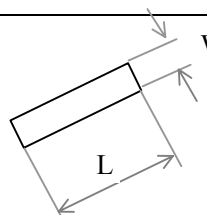
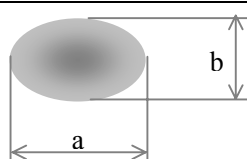
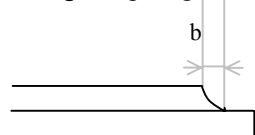
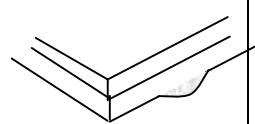
No.	Test Item	Test condition	Criterion
1	High Temperature Storage	80℃±2℃ 96H Restore 4H at 25℃	1. After testing, cosmetic defects should not happen. 2.Total current consumption should not be over 10% of initial value.
2	Low Temperature Storage	-30℃±2℃ 96H Restore 4H at 25℃	
3	High Temperature Operation	70℃±2℃ 48H Restore 4H at 25℃	
4	Low Temperature Operation	-20℃±2℃ 48H Restore 4H at 25℃	
5	High Temperature /Humidity Storage	40℃±2℃ 90%RH 48H	
6	Temperature Cycle	-30℃↔25℃↔80℃ 5min 30min ↔25℃ , 5min after 10cycle, Restore 4H at 25℃	Not allowed cosmetic and electrical defects.
7	Vibration Test (package state)	10Hz~150Hz, 100m/s ² , 120min	
8	Shock Test (package state)	Half- sine wave, 300m/s ² , 18ms	
9	Atmospheric Pressure Test	25kPa 16H Restore 2H	More than 50000 times
10	Cable Bending Test	Bending area and angle follow design document requirement	

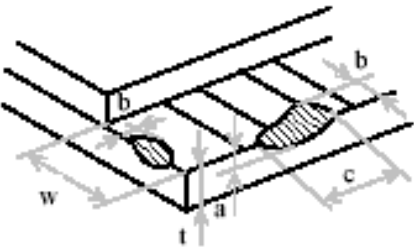
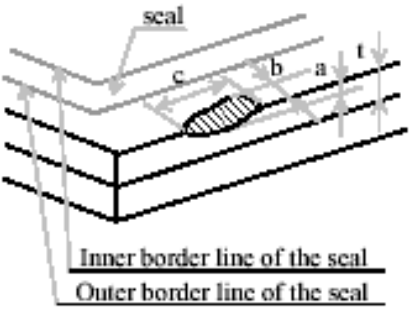
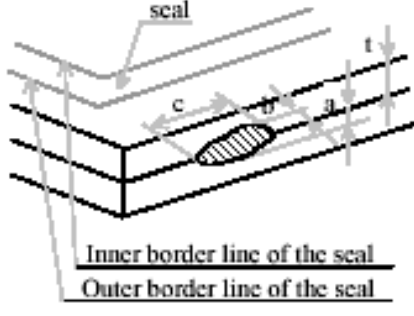
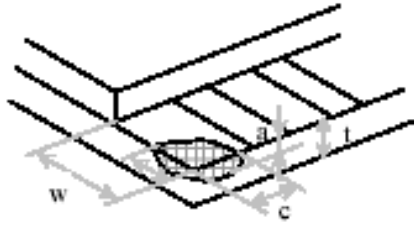
8 Quality level

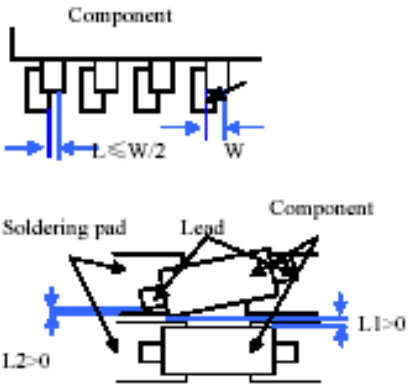
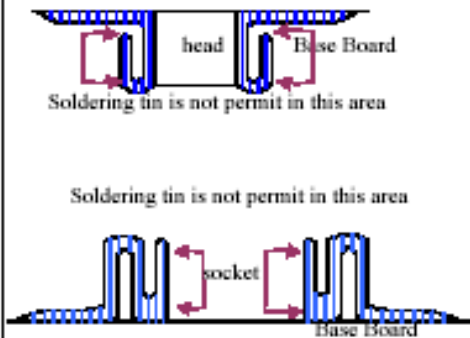
8.1 Notes for quality standard

	Note	
General	1. Should any defects which are not specified in this standard happen, additional standard shall be determined by mutual agreement between customer and Tianma. 2. Viewing Area should be the area which Tianma guarantees. 3. Limited sample should be prior to this Inspection standard. 4. Viewing Judgement should be under static pattern. 5. Inspection conditions Inspection distance : 250 mm (from the sample) Temperature : 25±5℃ Inspection angle : 45degrees in LCD view direction	
Definitions of Inspection items	Pinhole, Bright spot, Black spot, White spot, Black line, White Line, Foreign particle, Bubble	The color of a small area is different from the remainder. The phenomenon dose not change with voltage.
	Contrast variation	The color of a small area is different from the remainder. The phenomenon changes with voltage.
	Polarizer defect	Scratch, Dirt, Particle, Bubble on polarizer or between polarizer and glass.
	Glass defect	Glass crack, Shaved corner of glass, Surplus glass
Definitions of Inspection ranges	 Dividing A zone and B zone proceed to make a judgment. A zone : Inside Viewing area B zone : Outside Viewing area X1(A.A~V.A): mm X2(A.A~V.A): mm Y1(A.A~V.A): mm Y2(A.A~V.A): mm	
Outgoing Inspection standard	Inspection level II Normal Inspection. Sampling standard conforms to GB2828	
	Rank	Inspection Item
	Major defect	All Functional defects(Such as No display, Display abnormally, Open or missing segment, Short circuit, Missing component, No sound, Blight abnormally),Outline dimension beyond the drawing
	Minor defect	Appearance defects, such as Black/White spot, Bright spot, Pinhole, Black/White line, Contrast variation, Bubble Glass defect, Polarizer defect, and so on. Details of the standard as follows.

8.2 Standards of inspection items

Inspection item			Judgement standard			
			Category		Acceptable number	
					A zone	B zone
1	Black spot, White spot Bright Spot, Pinhole Foreign Particle, Bubble and Particle Between polarizer and glass, Scratch on polarizer	 $\Phi=(a+b)/2(\text{mm})$	A	$\Phi \leq 0.15$	Neglecte	Neglected
			B	$0.15 < \Phi \leq 0.20$	2	
			C	$0.20 < \Phi \leq 0.30$	1	
			D	$0.30 < \Phi$	0	
			Total defective point(B,C)		3	
2	Black line, White line, Bubble and Particle Between Polarizer and glass, Scratch on polarizer	 W:Width, L:Length(mm)	A	$W \leq 0.10$	Neglected	Neglected
			B	$0.01 < W \leq 0.03 \quad L \leq 3.0$	2	
			C	$0.03 < W \leq 0.05 \quad L \leq 3.0$	1	
			D	$0.05 < W$	0	
			Total defective point(B,C)		2	
3	Contrast variation	 $\Phi=(a+b)/2(\text{mm})$	A	$\Phi \leq 0.2$	Neglected	Neglected
			B	$0.2 < \Phi \leq 0.3$	2	
			C	$0.3 < \Phi \leq 0.4$	1	
			D	$0.4 < \Phi$	0	
			Total defective point(B,C)		3	
4	Bubble inside cell		any size		none	none
5	Polarizer defect (if Polarizer is used)	Scratch and damage on polarizer, Particle on polarizer or between polarizer and glass. Bubble, dent and convex	Refer to item 1 and item 2.			
			A	$\Phi \leq 0.3$	Neglected	Neglected
			B	$0.3 < \Phi \leq 0.7$	2	
			C	$0.7 < \Phi$	0	
			Total defective point(B,C)		2	
6	Surplus glass	①Stage surplus glass 	$b \leq 0.3\text{mm}$			
		②Surrounding surplus glass 	Should not influence outline dimension and assembling.			

Inspection item			Judgment standard	
			Category(application: B zone)	
7	Glass defect crack	①The front of lead terminals	A	If $a \leq t$ and $b \leq 1.0$, c is not limited
			B	$a \leq t$, $1 \leq b \leq 2\text{mm}$, $c \leq 3\text{mm}$
			C	If glass crack cover alignment mark, $b \leq 0.5\text{mm}$.
			D	Crack at two sides of lead terminals should not cover patterns and alignment mark
		②Surrounding crack—non-contact side	$b < \text{Inner borderline of the seal}$	
				
		③ Surrounding crack— contact side	$b < \text{Outer borderline of the seal}$	
				
		④Corner	A	$a \leq t$, $b \leq 3.0$, $c \leq 3.0$
			*Glass crack should not cover patterns used for	

Inspection item			Judgement standard
8	PCB defect	Component soldering: No cold soldering, short, open circuit, burr, tin ball The flat encapsulation component position deviation must be less than 1/2 width of the pin (Pic.1); the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2)	 Component $L \leq W/2$ Soldering pad Lead Component $L1 > 0$ $L2 > 0$
		lead defect: The lead lack must be less than 1/2 of its width; The lead burr must be less than 1/2 of the seam; Impurities connect with the near leads is not permitted	
		Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted	 head Base Board Soldering tin is not permit in this area Soldering tin is not permit in this area socket Base Board

9. Precautions for Use of LCD Modules

9.1 Handling Precautions

9.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.

9.1.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.

9.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.

9.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.

9.1.5 If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:

— Isopropyl alcohol

— Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

— Water

— Ketone

— Aromatic solvents

9.1.6 Do not attempt to disassemble the LCD Module.

9.1.7 If the logic circuit power is off, do not apply the input signals.

9.1.8 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

a. Be sure to ground the body when handling the LCD Modules.

b. Tools required for assembly, such as soldering irons, must be properly ground.

c. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.

- d. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

9.2 Storage precautions

9.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.

9.2.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature : $0^{\circ}\text{C} \sim 40^{\circ}\text{C}$

Relatively humidity: $\leq 80\%$

9.2.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.

9.3 The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.